

**8/16-bit Data Bus
Mask ROM Card**

**MF72M1 - G7DATXX
MF74M1 - G7DATXX**

Connector Type

Two-piece 68-pin

DESCRIPTION

Mitsubishi's MASK ROM cards provide large memory capacities on a device approximately the size of a credit card (85.6mm×54mm×3.3mm). The cards use a 8/16-bit data bus. Available 2 MB, 4 MB capacities. Mitsubishi's MASK ROM cards are available with a 68 pin, two-piece connector.

- 68-pin connector
- 8/16 bit controllable data bus width
- JEIDA ver 4/4.1 (PCMCIA2.0) compatible
- No attribute memory

FEATURES

- Uses TSOP (Thin Small Outline Package) to achieve very high memory density coupled with high reliability, without enlarging card size
- Electrostatic discharge protection to 15kV

APPLICATIONS

- Office automation
- Computers
- Telecommunications
- Data Communications
- Industrial
- Consumer

PRODUCT LIST

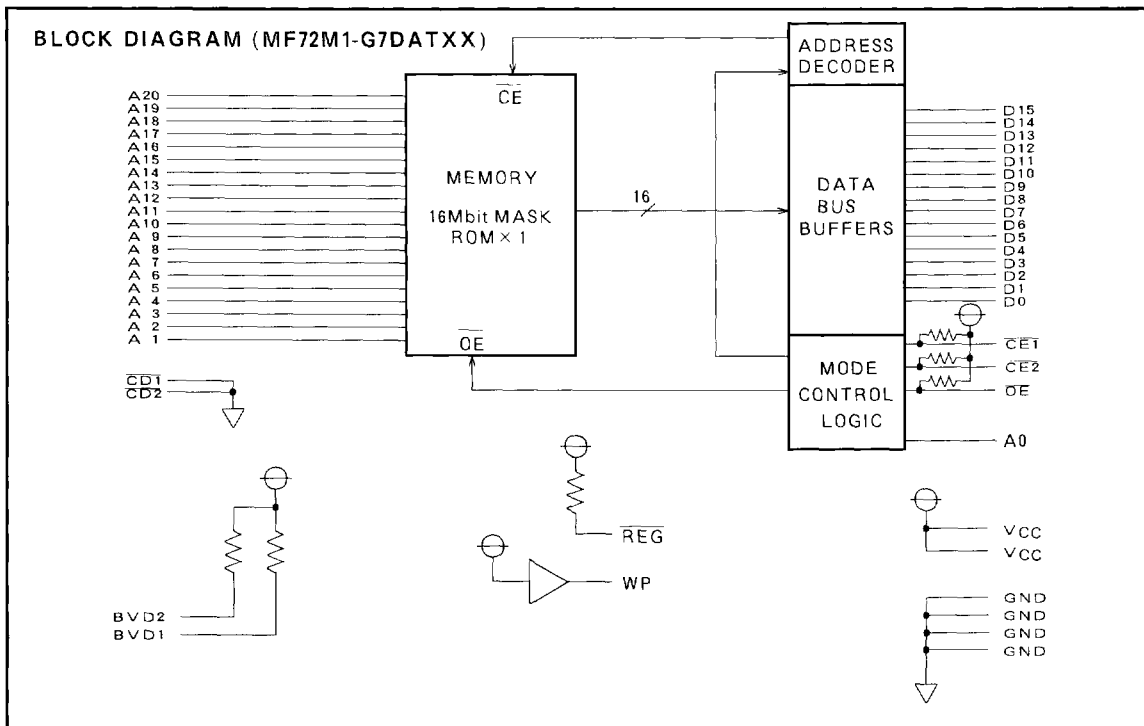
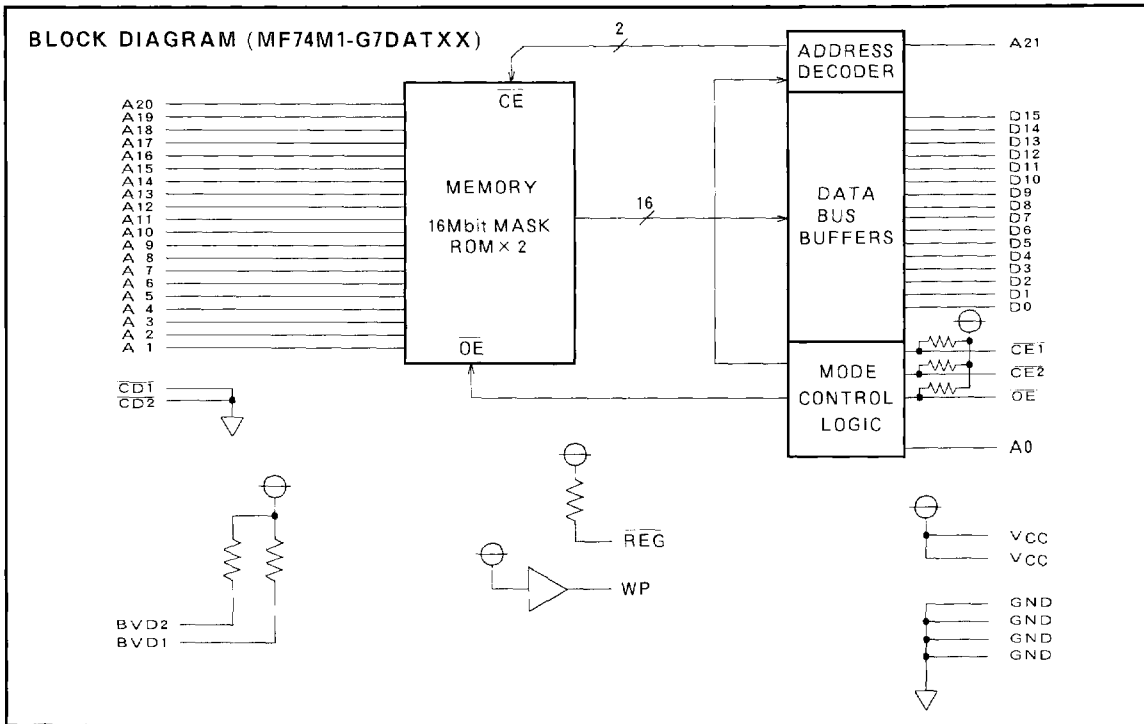
Type name	Item	Memory capacity	Data Bus width (bits)	Access time (ns)	Connector type	Number of pins	Outline drawing
MF72M1-G7DATXX		2 MB	8/16	200	Two-piece	68	68P-001
MF74M1-G7DATXX		4 MB					

MASK ROM CARDS

PIN ASSIGNMENT

Two-Piece Type (68-pin)

Pin No.	Symbol	Function	Pin No.	Symbol	Function
1	GND	Ground	35	GND	Ground
2	D 3	Data I/O	36	CD 1	Card detect 1
3	D 4		37	D11	Data I/O
4	D 5		38	D12	
5	D 6		39	D13	
6	D 7		40	D14	
7	CE 1	Card enable 1	41	D15	Card enable 2
8	A10	Address input	42	CE 2	
9	OE	Output enable	43	NC	No connection
10	A11	Address input	44	NC	
11	A 9		45	NC	
12	A 8		46	A17	Address input
13	A13		47	A18	
14	A14	48	A19		
15	NC	No connection	49	A20	A21 (NC for ≤ 2 MB types)
16	NC	No connection	50	A21	
17	V _{CC}	Power supply voltage	51	V _{CC}	Power supply voltage
18	NC	No connection	52	NC	No connection
19	A16	Address input	53	NC	
20	A15		54	NC	
21	A12		55	NC	
22	A 7		56	NC	
23	A 6		57	NC	
24	A 5		58	NC	
25	A 4		59	NC	
26	A 3	60	NC		
27	A 2	61	REG	REG function	
28	A 1	62	BVD 2	Battery voltage detect 2	
29	A 0	63	BVD 1	Battery voltage detect 1	
30	D 0	Data I/O	64	D 8	
31	D 1		65	D 9	
32	D 2		66	D10	
33	WP		Write protect	67	CD 2
34	GND	Ground	68	GND	Ground



MASK ROM CARDS

FUNCTION TABLE

Mode	$\overline{CE} 1$	$\overline{CE} 2$	\overline{OE}	A 0	I/O (D15~D 8)	I/O (D 7 ~D 0)	I _{cc}
Standby	H	H	X	X	High-impedance	High-impedance	Standby
Read A (16bit) Common	L	L	L	X	Odd byte Data out	Even Byte Data out	Active
Read B (8 bit) Common	L	H	L	L	High-impedance	Even Byte Data out	Active
	L	H	L	H	High-impedance	Odd byte Data out	Active
Read C (8 bit) Common	H	L	L	X	Odd byte Data out	High-impedance	Active
Output disable	X	X	H	X	High-impedance	High-impedance	Active

Note 1 : H = V_{IH}, L = V_{IL}, X = V_{IH} or V_{IL}.

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
V _{CC}	Supply voltage	With respect to GND	-0.3~+ 6.0	V
V _I	Input voltage		-0.3~V _{CC} +0.3	V
V _O	Output voltage		0 ~V _{CC}	V
T _{opr}	Operating temperature		0 ~70	°C
T _{stg}	Storage temperature		-30~80	°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
V _{CC}	V _{CC} supply voltage	4.75	5	5.25	V
T _a	Operating temperature	0		55	°C

MASK ROM CARDS

DC ELECTRICAL CHARACTERISTICS (T_a = 0 ~ 55°C, V_{CC} = V_{pp} = 4.75 ~ 5.25V, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
V _{IH}	High input voltage		2.4		V _{CC}	V
V _{IL}	Low input voltage		0		0.8	V
V _{OH}	High output voltage	I _{OH} = -1.0mA (except BVD1, 2)	2.4			V
V _{OL}	Low output voltage	I _{OL} = 2.0mA			0.4	V
I _{IH}	High input current	V _i = V _{CC} V			10	μA
I _{IL}	Low input current	V _i = 0 V	CE 1, CE 2, OE, REG	-10	-70	μA
			Other inputs		-10	
I _{OZH}	High output current in off state	CE 1 = CE 2 = V _{IH} or OE = V _{IH} , V _O = V _{CC}			10	μA
I _{OZL}	Low output current in off state	CE 1 = CE 2 = V _{IH} or OE = V _{IH} , V _O = 0 V			-10	μA
I _{CC1-1}	Active supply current 1	CE 1 = CE 2 = V _{IL} , Other inputs = V _{IH} or V _{IL} , Outputs = open	2MB		140	mA
			4MB		150	
I _{CC1-2}	Active supply current 2	CE 1 = CE 2 ≤ 0.2V, Other inputs ≤ 0.2V or ≥ V _{CC} - 0.2V, Outputs = open	2MB		120	mA
			4MB		130	
I _{CC2-1}	Standby supply current	CE 1 = CE 2 = V _{IH} , Other inputs = V _{IH} or V _{IL}	2MB		10	mA
			4MB			
I _{CC2-2}	Standby supply current	CE 1 = CE 2 ≥ V _{CC} - 0.2V, Other inputs ≤ 0.2 or ≥ V _{CC} - 0.2V	2MB		0.5	mA
			4MB		1	

Note 2 : Direction for currents flowing into IC card is indicated as positive (no mark).

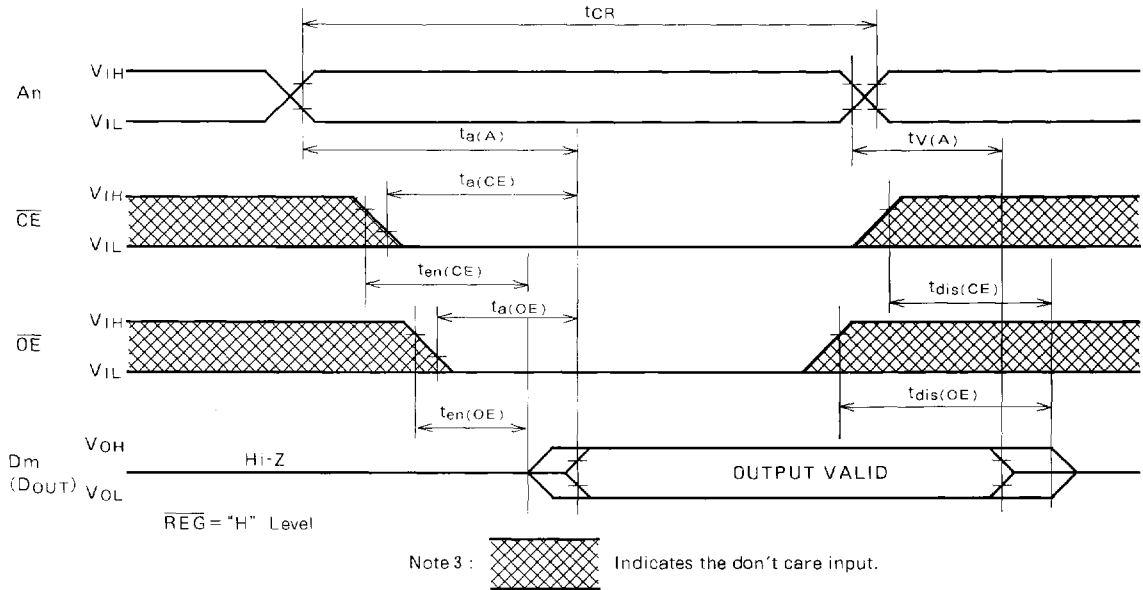
AC ELECTRICAL CHARACTERISTICS (COMMON MEMORY)

Read Cycle (T_a = 0 ~ 55°C, V_{CC} = 4.75 ~ 5.25V, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
t _{CR}	Read cycle time	200			ns
t _{a(A)}	Address access time			200	ns
t _{a(CE)}	Card select access time			200	ns
t _{a(OE)}	Output enable access time			100	ns
t _{dis(CE)}	Output disable time (from CE)			90	ns
t _{dis(OE)}	Output disable time (from OE)			90	ns
t _{en(CE)}	Output enable time (from CE)	5			ns
t _{en(OE)}	Output enable time (from OE)	5			ns
t _{v(A)}	Data valid time after address change	0			ns

TIMING DIAGRAM (COMMON MEMORY)

Read Cycle



Note 4 : Test Conditions

Input pulse levels : $V_{IL} = 0.4V$, $V_{IH} = 2.8V$

Input pulse rise, fall time : $t_r = t_f = 20ns$

Reference voltage

Input : $V_{IL} = 0.8V$, $V_{IH} = 2.4V$

Output : $V_{OL} = 0.8V$, $V_{OH} = 2.0V$

(t_{en} and t_{dis} are measured when output voltage is $\pm 500mV$ from steady state.)

Load : 100pF + 1 TTL gate

5 pF + 1 TTL gate (at t_{en} and t_{dis} measuring)

5 : \overline{CE} indicates as follows :

Read A/Write A : $\overline{CE} = \overline{CE1} = \overline{CE2}$

Read B/Write B : $\overline{CE} = \overline{CE1}$, $\overline{CE2} = "H"$ level

Read C/Write C : $\overline{CE} = \overline{CE2}$, $\overline{CE1} = "H"$ level

CAPACITANCE

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
C _i	Input capacitance	V _I = GND, V _I = 25mVrms, f = 1 MHz, T _a = 25°C	2 MB		50	pF
			4 MB			
C _o	Output capacitance	V _O = GND, V _O = 25mVrms, f = 1 MHz, T _a = 25°C	2 MB		45	pF
			4 MB			

Note 6 : These items are not 100% tested.